

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-26 (canceled)

27. (previously presented) An apparatus, comprising:
an electrically conductive trace on a substrate, the electrically conductive trace including an alloy of first and second materials, the alloy formed by applying a laser beam to the first material disposed on the second material; and diffusing a portion of the first material into a portion of the second material responsive to said applying, and wherein the first material includes a polymer epoxy.
28. (previously presented) The apparatus of claim 27, wherein:
the substrate is part of one of a semiconductor package, a printed circuit board, or a die.
29. (previously presented) The apparatus of claim 27, wherein:
the second material includes metal.
30. (previously presented) The apparatus of claim 27, wherein:
the second material includes copper.

31. (previously presented) The apparatus of claim 27, wherein:
the first material includes tin.

32. (previously presented) The apparatus of claim 27, wherein the polymer epoxy
comprises at least one of nitrogen or bromine.